



Material Content Data Sheet



Sales Product Name		IPD35N10S3L-26		Issued		29. August 2013		
MA#		MA000427194						
Package		PG-TO252-3-11		Weight*		370.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.969	0.80	0.80	8012	8012
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		633	
	inorganic material	phosphorus	7723-14-0	0.070	0.02		190	
	non noble metal	copper	7440-50-8	234.187	63.20	63.28	631890	632713
wire	non noble metal	aluminium	7429-90-5	1.864	0.50	0.50	5031	5031
encapsulation	organic material	carbon black	1333-86-4	1.252	0.34		3377	
	plastics	epoxy resin	-	21.904	5.91		59101	
	inorganic material	silicondioxide	60676-86-0	102.008	27.52	33.77	275241	337719
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10092	10092
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246
solder	noble metal	silver	7440-22-4	0.057	0.02		155	
	non noble metal	tin	7440-31-5	0.046	0.01		124	
	non noble metal	lead	7439-92-1	2.190	0.59	0.62	5908	6187
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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